



# INTERNATIONAL STANDARD



BASIC EMC PUBLICATION

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**Electromagnetic compatibility (EMC) –  
Part 4-23: Testing and measurement techniques – Test methods for protective  
devices for HEMP and other radiated disturbances**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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## CONTENTS

FOREWORD.....	6
INTRODUCTION.....	8
1 Scope.....	9
2 Normative references .....	9
3 Terms and definitions .....	10
4 HEMP test concepts .....	15
4.1 General.....	15
4.2 Testing of shielding enclosures .....	16
4.2.1 General .....	16
4.2.2 Buildings .....	19
4.2.3 Shelters and shielded rooms.....	20
4.2.4 Cabinets, racks and boxes.....	21
4.3 Testing of shielded cables and connectors.....	23
4.3.1 General .....	23
4.3.2 Testing of cable shields .....	23
4.3.3 Testing of cable connectors .....	26
4.4 Testing of shielding materials.....	27
4.4.1 General .....	27
4.4.2 Conducting gaskets .....	27
4.4.3 Conducting sheets and screens .....	29
4.4.4 Cut-off waveguides and honeycombs.....	32
4.5 Summary of test concepts.....	33
5 Test methods for measuring the shielding effectiveness of HEMP protection facilities.....	34
5.1 General.....	34
5.2 Electromagnetic field testing .....	34
5.2.1 General .....	34
5.2.2 Pulse field testing .....	34
5.2.3 CW field testing .....	40
5.3 Current injection test procedures .....	55
5.3.1 General .....	55
5.3.2 Injection testing of enclosures .....	55
5.3.3 Transfer impedance and admittance of cable shields and connectors .....	57
5.3.4 Testing of gasket material.....	57
Annex A (informative) HEMP test concepts for electrical systems .....	60
A.1 Overview.....	60
A.2 Types of HEMP tests .....	60
A.2.1 General .....	60
A.2.2 System-level transient tests .....	60
A.2.3 CW field illumination tests .....	61
A.2.4 Current injection testing.....	61
A.2.5 Partial illumination testing.....	62
A.2.6 Subsystem and component testing .....	62
A.3 Definition of the testing interface.....	63
A.4 Use of test data .....	65
A.4.1 General .....	65

A.4.2	Acceptance of new systems.....	65
A.4.3	System assessments .....	65
A.4.4	Hardness surveillance monitoring .....	65
A.4.5	System design.....	65
A.5	Testing uncertainties.....	66
Annex B (informative)	Characterization of shielded cables .....	67
B.1	Fundamentals of cable shielding .....	67
B.2	Definitions of transfer impedance and transfer admittance .....	68
B.3	Relative significance of $Z'_t$ and $Y'_t$ .....	71
Annex C (informative)	Equipment for HEMP pulse measurements.....	72
C.1	General.....	72
C.2	Sensors for HEMP measurements.....	72
C.2.1	<i>B</i> - and <i>H</i> -field sensors .....	72
C.2.2	<i>D</i> - and <i>E</i> -field sensors .....	74
C.2.3	Current sensors .....	76
C.3	Signal transmission.....	77
C.3.1	General .....	77
C.3.2	Fibre optic links .....	77
C.3.3	Fibre optic transducers .....	78
C.4	Signal detection and processing .....	78
Annex D (informative)	Equipment for CW testing .....	80
D.1	General.....	80
D.2	Antenna system .....	80
D.3	Power amplifier .....	82
D.4	Receiver (network analyser).....	83
D.5	Reference and response sensors.....	83
D.6	Fibre optic system.....	85
D.7	Limitations of measurements .....	88
Annex E (informative)	Characterization of a planar shield for HEMP protection.....	89
E.1	General.....	89
E.2	Problem geometry.....	90
E.3	Equivalent circuit representation .....	91
E.3.1	General .....	91
E.3.2	Chain parameter representation of the shield.....	92
E.3.3	Circuit responses.....	93
Annex F (informative)	Inside-to-out measurement method .....	97
F.1	Purpose .....	97
F.2	Comparison of existing SE test methods .....	97
F.3	Inside-to-out SE test of shielded rooms.....	98
F.3.1	Measurements of the inside-to-out SE .....	98
F.3.2	Summary .....	101
Bibliography.....		102

Figure 1 – Example of measured magnitude and phase of the transfer function  $T(\omega) = H_{in}/H_{out}$  for a shielded enclosure ..... 17

Figure 2 – Electric field and magnetic field shielding effectiveness of a 0,5 mm thick aluminum enclosure [29]..... 18

Figure 3 – Measured magnetic field shielding effectiveness  $SE_H$  for a building..... 19

Figure 4 – Conceptual illustration of the HEMP test of a building .....	19
Figure 5 – Illustration of a shielded room or enclosure excited by HEMP fields .....	21
Figure 6 – Illustration of equipment racks, cabinets and box excited by internal HEMP disturbance.....	21
Figure 7 – A general shield excited by current injection .....	22
Figure 8 – Basic configuration for transfer impedance measurement.....	24
Figure 9 – Measured transfer impedance magnitude and phase of transfer impedance per unit length for four braided shield cables with good shielding properties .....	25
Figure 10 – Basic configuration for transfer admittance measurement.....	26
Figure 11 – Test configuration for transfer impedance measurement of a cable connector.....	26
Figure 12 – Examples of conducting gaskets used as HEMP protection devices .....	28
Figure 13 – Circuit model representing the behaviour of a conducting gasket for HEMP protection .....	28
Figure 14 – Measurement configuration for the resistivity of a sample.....	29
Figure 15 – Test concept for measuring the resistivity with surface probes .....	30
Figure 16 – Concepts for shielding effectiveness measurement of conducting sheets and screens .....	32
Figure 17 – Example of the calculated plane-wave shielding effectiveness of a 0,01 mm thick plate of different material as a function of frequency .....	32
Figure 18 – Cut-off waveguides and honeycomb used as protective elements.....	33
Figure 19 – Examples of full-scale, pulse-radiating HEMP simulators.....	37
Figure 20 – Test procedure for the pulse test.....	39
Figure 21 – Typical configuration of a CW test facility .....	40
Figure 22 – Example CW measurement set-up .....	41
Figure 23 – Test and analysis procedures for conducting a CW test.....	42
Figure 24 – Analysis flow diagram for extrapolating a measured CW spectrum to the HEMP response.....	43
Figure 25 – Example scan from 9 kHz to 3 GHz for the ambient electromagnetic field from communication signals.....	44
Figure 26 – Test procedure for the ambient EM excitation test .....	45
Figure 27 – Double-ended TEM cell for field illumination testing of small enclosures .....	46
Figure 28 – Example test set-up for field illumination in the TEM cell .....	47
Figure 29 – Illustration of the single-ended TEM cell and associated equipment .....	48
Figure 30 – Test set-up for the plane-wave shielding effectiveness measurements .....	50
Figure 31 – Test set-up for the <i>H</i> -field shielding effectiveness measurements.....	51
Figure 32 – Example of antenna locations for the localized antenna tests for a hypothetical shielded enclosure or facility .....	52
Figure 33 – Test concept and equipment configuration for current injection testing of a shielded enclosure or box .....	56
Figure 34 – Surface probe for volume resistivity measurement .....	59
Figure A.1 – Sample HEMP interaction diagram illustrating penetration mechanisms, system responses and generic test interface locations .....	64
Figure B.1 – Geometry of a shielded coaxial line with an internal circuit .....	67
Figure B.2 – Coaxial cable located over a conducting ground plane .....	68
Figure B.3 – Two per-unit-length circuits formed by the sheath and its ground return, and the sheath and the internal conductor .....	69

Figure C.1 – Magnetic field sensors [23] .....	73
Figure C.2 – Single-slot, cylindrical coil sensor [23] .....	73
Figure C.3 – Two- and four-slot cylindrical coil sensors [23].....	74
Figure C.4 – Electrical configuration of an $E$ -field sensor [23] .....	74
Figure C.5 – Biconical $E$ -field sensor .....	75
Figure C.6 – $E$ -field sensor mounted on a conducting ground plane [23] .....	75
Figure C.7 – Equipotential shapes for an optimally designed $E$ -field sensor [23] .....	75
Figure C.8 – Rogowski coil used for current measurements [23] .....	76
Figure C.9 – Toroidal current sensor made of magnetic material [23].....	76
Figure C.10 – Voltage pick-up points on the edges of the toroidal sensor [23].....	76
Figure C.11 – Example of a single-channel fibre optic transmission system [23] .....	77
Figure C.12 – Attenuation of coaxial lines and fibre optic cables as a function of frequency.....	78
Figure D.1 – Various antennas for CW testing.....	81
Figure D.2 – Relationship between the CW antenna and the incident HEMP field .....	82
Figure D.3 – Incident and ground-reflected field contributions to the reference sensor excitations .....	84
Figure D.4 – Measured reference $H$ -field spectrum and its inverse Fourier transform .....	85
Figure D.5 – Measured sensor responses and calibration function .....	87
Figure D.6 – Measured transfer function, corrected by calibration file .....	87
Figure E.1 – Example of a general shielding problem.....	89
Figure E.2 – Behaviour of the impedance ratio $EH$ as a function of distance from a source [29].....	90
Figure E.3 – Conducting slab of thickness, $d$ , and infinite extent serving as an electromagnetic barrier .....	91
Figure E.4 – Equivalent circuit representation of the shielding problem .....	92
Figure E.5 – Two-port representation of a circuit.....	93
Figure F.1 – Test set-up for the outside-to-in and inside-to-out SE measurement.....	100
Table 1 – Recommended test procedure for different test objects .....	34
Table 2 – Dimensions and composition of distances $d_1$ to $d_3$ , with reference to Figure 30 ....	50
Table 3 – Dimensions and composition of distances $d_1$ to $d_3$ , with reference to Figure 31 ....	51
Table 4 – Measurement frequencies and antennas in plane-wave.....	52
Table 5 – Measurement frequencies and antennas in magnetic field.....	54
Table E.1 – Surface resistance and electrical parameters for selected materials.....	95
Table F.1 – Comparison with other standards .....	98
Table F.2 – Test shielded rooms .....	99
Table F.3 – Comparison of the SE measurement results.....	101

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

### **ELECTROMAGNETIC COMPATIBILITY (EMC) –**

### **Part 4-23: Testing and measurement techniques – Test methods for protective devices for HEMP and other radiated disturbances**

#### FOREWORD

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International Standard IEC 61000-4-23 has been prepared by subcommittee 77C: High power transient phenomena, of IEC technical committee 77: Electromagnetic compatibility.

It forms Part 4-23 of IEC 61000. It has the status of a basic EMC publication in accordance with IEC Guide 107.

This second edition cancels and replaces the first edition published in 2000. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) updates to the shielding effectiveness (SE) test method in Clause 5;
- b) a new Annex F describing methods for testing 'inside-to-out' has been added.

The text of this standard is based on the following documents:

CDV	Report on voting
77C/253/CDV	77C/257/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61000 series, published under the general title *Electromagnetic compatibility (EMC)*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

**IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.**

## INTRODUCTION

IEC 61000 is published in separate parts, according to the following structure:

### **Part 1: General**

General considerations (introduction, fundamental principles)  
Definitions, terminology

### **Part 2: Environment**

Description of the environment  
Classification of the environment  
Compatibility levels

### **Part 3: Limits**

Emission limits  
Immunity limits (in so far as they do not fall under the responsibility of the product committees)

### **Part 4: Testing and measurement techniques**

Measurement techniques  
Testing techniques

### **Part 5: Installation and mitigation guidelines**

Installation guidelines  
Mitigation methods and devices

### **Part 6: Generic Standards**

### **Part 9: Miscellaneous**

Each part is further subdivided into several parts, published either as international standards, as technical specifications or technical reports, some of which have already been published as sections. Others will be published with the part number followed by a dash and a second number identifying the subdivision (example: IEC 61000-6-1).

The IEC has initiated the preparation of standardized methods to protect civilian society from the effects of high power electromagnetic (HPEM) environments. Such effects could disrupt systems for communications, electric power, information technology, etc.

This part of IEC 61000 is an international standard that establishes the test concepts, set-ups, required equipment, and test procedures for protective devices against HEMP radiated disturbances.

Annex F provides examples of the SE test method placing the TX antenna inside the barrier.



## **ELECTROMAGNETIC COMPATIBILITY (EMC) –**

### **Part 4-23: Testing and measurement techniques – Test methods for protective devices for HEMP and other radiated disturbances**

#### **1 Scope**

This part of IEC 61000 provides a protective devices test method for HEMP and other radiated disturbances. It is primarily intended for HEMP testing but can be applied to other externally generated radiated disturbances where appropriate. It provides a brief description of the most important concepts for testing of shielding elements. For each test, the following basic information is provided:

- theoretical foundation of the test (the test concepts);
- test set-up including outside-to-in and inside-to-out measurements;
- required equipment;
- test procedures;
- data processing.

This international standard does not provide information on requirements for specific levels for testing.

This part of IEC 61000 has been updated to include a new test method.

Due to the available space, a transmitting antenna position outside the barrier has mainly been suggested. However, nowadays, many EMP protection facilities in practical use do not actually have enough space available outside the electromagnetic barrier due to physical constraints such as concrete walls or soil to allow the method described in IEC 61000-4-23:2000 (edition 1) to be applied correctly. From experience many facilities have available space for a 1 m separation or less only.

Therefore, in many practical cases it is not possible to measure shielding effectiveness according to the test method of previous documents. The constructors for EMP protection facilities are also unwilling to build facilities with extra space for measurements with the transmitting antenna outside the barrier due to the great expense and inefficiency of the operational working area for new or existing buildings.

This document provides additionally a method that allows the transmitting antenna to be placed inside the enclosure and the receiving antenna outside the barrier ('inside-to-out' method). Annex F includes test set-up and procedure examples.

#### **2 Normative references**

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-161, *International Electrotechnical Vocabulary (IEV) – Part 161: Electromagnetic compatibility* (available at [www.electropedia.org](http://www.electropedia.org))

IEC 61000-2-9, *Electromagnetic compatibility (EMC) – Part 2: Environment – Section 9: Description of HEMP environment – Radiated disturbance*

IEC 61000-5-3, *Electromagnetic compatibility (EMC) – Part 5-3: Installation and mitigation guidelines – HEMP protection concepts*